

Plaskon MUF-LFG

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy Molded UnderFill compound developed for transfer mold equipment to underfill, and overmold if needed, Flip Chip in Package (FC-BGA and FC-CSP) in one step. It offers high productivity with an automated, simple, robust and fast process compared to liquid encapsulation. Higher reliability is demonstrated with the material's higher Tg, lower CTE, no particle segregation or settling and longer outlife compared to liquid encapsulants. PLASKON? MUF is the total molded underfill solution for Flip Chip in Package.

General Information			
Features	Semi-conductive		
	Low warpage		
	Workability, good		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	2.00	g/cm ³	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	2.45	MPa	ASTM D790
260°C	0.0686	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0132	MPa	ASTM D790
260°C	0.00127	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	135	°C	ASTM E1356
CLTE - Flow	9.0E-6	cm/cm/°C	ASTM D696
Thermal Conductivity	0.70	W/m/K	ASTM C177
Flammability	Nominal Value		Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			
Recommended Storage Temperature: 5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 175°C, 1000 psi: 160 cmShimadzu Viscosity, 175°C, 1000 psi: 30 poiseRam Follower Gel Time, 175°C, 1000 psi: 25 secAsh Content: 87.5 %Hydrolyzable Halides: <1 ppmMoisture Absorption, 85°C/85%RH, 168 hrs: 0.25%Filler Size, Max in traces: 40 µFiller Size, average: 6 µCull Hot Hardness, Shore D: 65All test specimens are transfer molded and post cured for 4 hours at 175°C			
Linear Thermal Expansion, Alpha 1: 9 cm ⁻⁶ /cm/°C			
Linear Thermal Expansion, Alpha 2: 40 cm ⁻⁶ /cm/°C			
Injection instructions			

Resin Transfer Molding:
Molding Temperature: 165 to 185°C
Molding Pressure: 1000 psi
In Mold Cure Time: 50 to 100 sec
Post Mold Cure Time, 175°C: 0 to 2 hr

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Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519
Phone: +86 13424755533
Email: sales@su-jiao.com
No. 215, Lianhe North Road, Fengxian District, Shanghai, China

